

ACCU-LABS INC.

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A2LA Accredited ISO/IEC 17025:2005 Certificate # 2558.01

916 TLS NON-PEROXIDE TIN/LEAD STRIPPER

ACCU-LABS 916 was specifically developed as an efficient, safe, and convenient method for removing tin and tin/lead (solder) from finished printed circuit boards and copper based parts.

ACCU-LABS 916 is formulated to strip tin/lead without the use of hydrogen peroxide and free fluorides. It will not attack or alter a properly cured resin based board. Attack to copper undercoating and nickel is virtually non-existent.

COMPOSITION

916 is comprised of a balanced blend of acids, oxidants, and surface active agents.

OPERATING GUIDELINES:

CONCENTRATION

Use as is at full strength, at room temperature.

EQUIPMENT

Polyethylene, polypropylene, rubber or koroseal lined tanks.

BASKETS OR RACKS

Plastisol covered steel.

The following cycle is recommended for removing tin/lead plate from copper plated printed circuit boards or other copper based parts:

1. Strip in **ACCU-LABS 916** – Concentrated as is.
2. Cold water rinse.
3. Immerse parts in a 3% sulfuric acid solution if necessary.
4. Water rinse.
5. Clean parts prior to subsequent plating.
6. Cold water rinse.
7. Plate nickel and gold or other subsequent processing.

CAUTION:

ACCU-LABS 916 is a blend of strong acids and oxidants should be stored in a cool place away from any organic solvent. Personal protective gear including eye protection should be worn when working with or handling this product. Read MSDS prior to use.

DISCLAIMER:

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